DS280BR810 QSFP Reference Design

[Diagram showing the connections between Host, TOP, BOT, Cable, TOP, BOT, Stacked QSFP28 Connector, and Mini-USB.]
All differential traces are to be routed with 100 ohm differential impedance.
CLOCK AND POWER

2.5V SUPPLY REGULATOR, 3A MAX (INCLUDING BYPASS OPTION)

Silkscreen:
2.5V regulator disable, install jumper across, supplying 2.5V directly.

LAYOUT NOTE: Place LED near 2.5V banana jack (J14)

SILKSCREEN:
2.5V Power

LAYOUT NOTE: Place LED near 2.5V banana jack

SILKSCREEN:
Connect 2.5V Reg output to main 2.5V plane

LAYOUT NOTE: This header connects two power planes: the main 2.5V plane and the regulator's output plane.

LAYOUT NOTE: Bulk supply decoupling close to banana jack.

2.5V SUPPLY REGULATOR, 3A MAX (INCLUDING BYPASS OPTION)

Power binding posts should be 750mil apart

Layout bypass close to oscillator.

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